

IN THE CLAIMS:

Please amend the claims as follows:

1-2. (Canceled)

3. (Currently Amended) An electrochemical plating system comprising:
a substrate loading station positioned in communication with a mainframe processing platform;
at least one substrate plating cell positioned on the mainframe;
at least one substrate bevel cleaning cell positioned on the mainframe;
at least one spin rinse dry cell positioned on the mainframe in a substrate transfer path between the at least one substrate plating cell and the substrate loading station, wherein the at least one spin rinse dry cell comprises:
a cell bowl having an upstanding cylindrical wall;
an annular and inwardly curving pressure reducing surface positioned on a top portion of the upstanding cylindrical wall;
a fluid receiving shield attached to, and extending radially inward from, an upper portion of the upstanding cylindrical wall, wherein the fluid receiving shield has a plurality of holes;
a rotatable substrate support member centrally positioned in the cell bowl;
and
a fluid dispensing nozzle configured to dispense a rinsing solution onto an upper surface of a substrate positioned on the support member; and
a stacked substrate annealing station positioned in communication with at least one of the mainframe and the loading station, each chamber in the stacked substrate annealing station having a substrate heating plate and a substrate cooling plate adjacently positioned therein.

4-32. (Canceled)